

METHOD OF FABRICATING SEMICONDUCTOR HAVING THROUGH HOLE

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ABSTRACT OF THE DISCLOSURE

10 The semiconductor device includes a semiconductor  
chip, a tape for mounting the semiconductor chip thereto,  
an adhesive resin layer interposed between the  
semiconductor chip and the tape, and solder balls  
attached to the tape. The method of fabricating the  
semiconductor chip comprises the step of forming at least  
one hole in the tape, after fixing the semiconductor chip  
15 to the tape through the adhesive resin layer. Also, the  
TAB tape is made of polyimide having high water  
permeability.